The 3rd International Conference on Positioning Technology

International Conference on New Technological Innovation for Positioning

ICPT 2008 November 26-28, 2008 Congress Center Actity Hamamatsu, Shizuoka, Japan

Sponsored by

Technical Committee of Ultra Precision Positioning, JSPE

Korea Institute of Machinery and Materials

Participating Society

Korean Society for Precision Engineering (KSPE) Japan Society for Precision Engineering (JSPE) Institute of Electrical Engineers of Japan (IEEJ) Korean Ministry of Science and Technology (MOST) Japan Society of Mechanical Engineers (JSME) Society of Instrument and Control Engineers (SICE)

ICPT2008 aims to provide an atmosphere for researchers and engineers to discuss, exchange and expose ideas, methods and results in conventional, contemporary and future topics of positioning and ultraprecision positioning technologies. Following 2nd ICPT held in Jedu City Korea-finished in October, 2006, this international conference is held in the Japan side.

As an optional tour, the factory observation of the precision and ultra-precision technology related enterprise around Hamamatsu has also been scheduled.

The conference venue, Hamamatsu is the most renowned scientific-research city in Japan, which is emerging as one of the world's foremost IT (Information technology) countries. Living up to this reputation, the city is focusing on fostering and developing high-tech and knowledge-intensive industries. It takes 2 hours by bullet train from Tokyo and Osaka.

Topics

The conference focuses on the followings, but are not limited to:

- Actuators
- Actuators
- AssemblyApplications
- Control methods
- Case studies
- Data processing
- Materials and Mechanism
- Modeling

- Mechatronics
- Nanotechnology
- Positioning Design
- Positioning system
- Positioning components
- Sensors and measurement
 - Instruments
- Simulation

Language

English is the official language of the conference for all presentations and correspondence.

Abstract and Paper Submission

Authors should submit an abstract including the following: a) the title of a paper, b) author name(s) and affiliation(s), c) the corresponding author's name and title, d) his/her postal address, phone number, fax number and e-mail address, e) a 300-word abstract including brief backgrounds, objectives, methods and results, f) several keywords, g) a contribution type (long or short paper) and h) a presentation type (oral or poster). The inclusion of figures in the abstract is not

recommended. Papers, which have been published in another form elsewhere in either English or any other languages, are also welcome if they are reconstructed from new aspects.

The program committee will evaluate your proposals. Due to limited speaker slots, some papers may be accepted as poster presentations. All abstracts accepted will require one or more of the authors to attend the conference for the presentation.

A sample writing format is given in the latter page.

Important Dates

- The deadline of the abstracts in PDF is *June 25, 2008 July 25, 2008 (extended)* and they should be submitted by e-mail.
- Acceptance letters and author's kits for a camera-ready manuscript will be sent by *August 25, 2008*.
- Final camera-ready manuscripts for accepted papers must be sent by *September 25, 2008*.

They will be published in the conference proceedings as 2-page short papers or 6-page long papers.

Abstract and camera-ready manuscript must be sent to:

Chair of Program Committee

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Schedule

November 26: Conference meeting and banquet

27: Conference meeting

28: Factory tour

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Participation Fee

The participation fee is 20,000 Japanese Yen or 200,000 Korean Won. The participation fee for student participants is 5,000 Japanese yen or 50,000 Korean Won, but no charge for student speakers. This includes registrations, proceedings and banquet.

For more information, please contact:

ICPT2008 Secretariat

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ICPT 2008 Registration Form (Please print or type clearly.) Name: (Mr. / Ms. / Prof. / Dr.) (Family) (First) (Middle initial) Affiliation: Address / Postal code: Country: Telephone: Facsimile: E-mail: ☐ I herewith attach 3 copies of my abstract. □ I intend to present a paper and will submit an abstract shortly. Paper type: □ full paper □ short paper / Presentation type: □ oral □ poster Paper Title: Category of Paper Topics:

☐ I would like to have detail information of ICPT 2008

Please return to the programming committee.

☐ I would like to receive a registration packet for ICPT 2008.

How to Prepare Camera-ready Manuscript for the 3rd International Conference on Positioning Technology - Format and Style Guide-

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Abstract

This document provides information and instructions to prepare a final camera-ready manuscript for International the 1st Conference on Positioning Technology (ICPT2008). The style of this document also shows how your paper should be prepared. 300 words are allowed for long papers. Short papers do not need abstract. Do not cite references in the abstract. Several key words must be given for both long and short papers.

Key words: positioning, keep deadlines, actuator, style guide.

1. Introduction

1.1 Paper size

All authors are requested to prepare their camera-ready manuscript on white A4 (210 by 297 mm) papers. The manuscript should be written in English. A long paper is not exceeding 6 pages and a short paper is not exceeding 2 pages including figures, tables, references and appendices.

Please ensure that the format provided is closely followed and make sure that your paper is preferably edited by a person with good English writing skills.

1.2 Format

The main body of the text, including an abstract, should be typed with single spacing

and arranged in double column format. Top and

bottom margins are 25 mm and left and right ones are 20 mm. A gutter, which is a space between columns, is 8 mm. Columns should be both left and right justified. No indentation is required when starting a new paragraph.

Use either one or two spaces between sections, and between text and tables or figures, to adjust column length. Do not use spaces between paragraphs. Use automatic hyphenation, and check spelling and grammatical errors. Either digitize or paste down your figures and photographs.

Do not use a dot-matrix printer.

Do not insert page numbers as actual page numbers will be inserted by Program Committee. However, label each page at the top, right corner with your page count: "1/6," "2/6," etc. using a light blue (non-photo) pencil.

2. Font

2.1 Font size

Table 1 shows the font type used for both the long and short papers. One point is about 0.35 mm. If you do not have the fonts shown in Table 1, use similar fonts.

2.2 Title

Fonts for the main and the sub-titles should be

Table 1 Type styles and point sizes.

Part	Font	Size
Main title	Arial	18 pt
Sub title	Arial	16 pt
Author name(s)	Times New Roman	14 pt
Affiliation(s)	Times New Roman	12 pt
Abstract	Times New Roman	12 pt
Main text	Times New Roman	12 pt
Footnotes	Times New Roman	10 pt
Headings	Arial	12 pt
Sub-headings	Arial Italic	12 pt
Sub-sub-heading	Times New Roman	12 pt
S	Italic	•
References	Times New Roman	12 pt
Table and figure	Times New Roman	10 pt
captions		

18 pt and 16 pt Arial, respectively. It should be centered on the page with the first line at the top of the first page.

2.3 Authors

The font for name(s) of author(s) should be 14 pt Times New Roman. It (They) should be centered under the title with one line space separating the title from the author(s). Family (last) names should be capitalized. Authors' affiliation should include department or division, university or company name. The corresponding address should be indicated as a footnote. All authors' affiliation information should be typed in 10pt Times New Roman, upper and lower case letters. corresponding author should be designated with "*." The speaker of the paper must be underlined. The postal address, phone and fax address numbers, and e-mail of the corresponding author should be indicated below his/her affiliation.

2.4 Main body of text

The font size for the main body of the text should be 12 pt Times New Roman.

3. Main headings

Main headings should be centered and numbered sequencially. A full stop follows the heading number. Leave a single line space both above and below these headings.

3.1 Subheadings

Subheadings should be typed flush with the left-hand side of the column in lower case lettering except for the first letter of the first

word. Leave one line space above, with the text beginning on the next line below it.

3.1.1 Sub-subheadings

Sub-subheadings should be 12 pt Times New Roman Italic.

4. Footnotes

Footnotes should be avoided if possible.

Necessary footnotes should be placed at the bottom of the column to which they refer. Number footnotes separately in superscript¹. Do not put footnotes in the reference list. Footnotes are separated with a solid line of 1 pt in width and 50 mm in length. They are designated by superscript numerals and are numbered consecutively.

5. Equations

Equations should be typed. Number them consecutively with the number in parentheses, flush to the right.

$$m\frac{d^2x}{dt^2} + c\left(\frac{dx}{dt} - \frac{dy}{dt}\right) + kx = F(t)$$
 (1)

Avoid hand lettering of symbols and equations. Be sure that the symbols in your equation have been defined before the equation appears or immediately following. Refer to "(1)," not "Eq. (2)" or "Equation (3)," except at the beginning of a sentence: "Equation (4) is..."

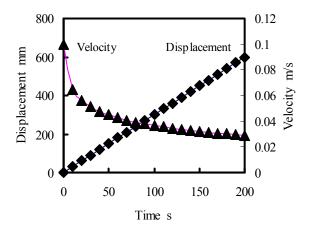
6. Illustrations and tables

Position figures and tables at the top or bottom of columns. Avoid placing them in middle of columns. Large figures and tables may span both columns.

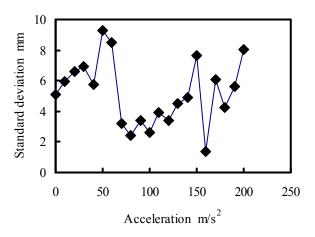
6.1 Illustrations

All line drawings and graphs should be drawn

¹ An example of a footnote. Footnotes should be avoided.



(a) Displacement and velocity



(b) Standard deviation
Fig. 1 Example of figures

clearly and legibly using a drawing package of your choice. Illustrations should be placed at the top of a column as close as possible to first reference to them.

Only clear and high quality photos with high contrast and resolution are acceptable. Color prints will be reproduced in black and white.

Each illustration should have a space of approximately 1 line below. The figure number and caption should be typed below the illustration. The word 'Figure' should be shortened to 'Fig.' at the beginning of the figure caption. It should also be shorten to 'Fig.' in the text except even at the beginning of a sentence.

6.2 Tables

Leave a space of one line after the text and type the table heading, including the table number, above the table.

Table headings should be centered and only the

first letter of the headings should be in capital letter. Leave a single line space between the heading and the table. A single line space should also be left after the table.

7. Units

Units used in the manuscript should be expressed in Standard International Unit (SI). An exception is when English units are used as identifiers in trade, such as "3.5-inch disk drive."

8. Citations of references

References should be numbered consecutively throughout the paper and be listed at the end of the paper with the main heading References. When referring to them in the text, type the corresponding number in square brackets [1]. The sentence punctuation follows the brackets [2]. Multiple references [3][4] are each numbered with separate brackets [5]-[10]. In sentences, refer simply to the reference number, as in [3]. Do not use "Ref. [3]" or "Reference [3]" except at the beginning of a sentence: "Reference [3] shows..."

In listing the references, follow the style for each kind of publication.

All authors should be included in the reference citation. The use of 'et al.' is not acceptable unless there are six authors or more.

Papers that have not been published, even if they have been submitted for publication, should be cited as "unpublished." Papers that have been accepted for publication should be cited as "in press." Please give affiliations and addresses for personal communications.

Capitalize only the first word in a paper title, except for proper nouns and element symbols. Paper titles are helpful to your readers and strongly recommended. Please give the English citation first, followed by the original foreign language citation.

9. Conclusion

Program committee decided to accept only a hardcopy of a camera-ready manuscript to avoid the change of layout and font problems.

The copyright of the papers must be transferred to the Technical Committee of Ultra Precision Positioning, Japan Society for Precision Engineering.

Late papers may not appear in the proceeding book

Authors are encouraged to submit a full paper manuscript to a journal after the conference if they have not submitted it to any journal.

Camera-ready manuscripts with a copyright transfer form must be sent:

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Acknowledgement

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References

- [1] L. C. Hale and A. H. Slocum: Optimal design techniques for kinematic couplings, Precision Engineering, 25 (2), pp. 114-127 (2001).
- [2] K. Furutani, M. Furuichi and N. Mohri: Coarse motion of 'seal mechanism' with three degrees of freedom, Measurement Science and Technology (in press).
- [3] J. Ootsuka, S. Hayama and Y. Oohashi: Present and future technologies of precision and ultraprecision positioning, Journal of Japan Society for Precision Engineering, 67(2), pp. 173-178 (2001) [in Japanese].
- [4] H. N. Kwon, J. H. Lee, S. H. Jeong and S. K. Lee: A micromachined thermoelastic inchworm actuator, Proceedings of 16th

- Annual Meeting of American Society for Precision Engineering, Arlington, VA, USA, pp. 127-130 (2001).
- [5] T. C. Chang, R. A. Wysk and H. P. Wang: Computer-aided manufacturing (2nd Ed.), Pretice Hall, NJ, USA, pp. 369-373 (1998).

Appendices

If authors intend to include an appendix, it should be placed after the references.